Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN170403 **Date:** February 02, 2017

Subject: Qualification of JCET as an Alternate Assembly Site and CML as an Alternate Test, Finish & Burn-In Site for Select 44-Lead TSOP II Package Products

To: TOKYO ELECTRON DEVICE
TELDEVICE
cy-inside@teldevice.co.jp

Description of Change:

Cypress announces the qualification of Jiangsu ChangJiang Electronics Technology Co., Ltd (JCET) as an alternate assembly site for select 44-Lead TSOP II (400mils) Pb-Free package products. JCET is a world-class assembly facility, qualified to build standard grade products consistent with AEC-Q100. The qualification of this facility will enable Cypress to tailor assembly operations to meet our customers' stringent quality and reliability requirements in our effort to continually provide world-class service.

44-Lead TSOP II (400mils) Pb-Free packages are assembled at JCET using the following Bill of Materials (BOM):

BOM for Marketing Part Numbers: FM22L16-55-TG & FM22L16-55-TGTR:

Material	JCET Bill of Materials	ASE-KH Bill of Materials
Mold Compound	Sumitomo EME-G620B	Sumitomo EME-G631H
Lead Finish	Matte Tin	Matte Tin
Die Attach Epoxy	Henkel QMI509	Sumitomo CRM-1076WA
Bond Wire	0.8mil PdCu	0.8mil Au

BOM for Marketing Part Numbers: FM28V102A-TG, FM28V102A-TGTR, FM28V202A-TG and FM28V202A-TGTR

Material	JCET Bill of Materials	ASE-KH Bill of Materials
Mold Compound	Sumitomo EME-G620B	Sumitomo EME-G631H
Lead Finish	Matte Tin	Matte Tin
Die Attach Epoxy	Henkel QMI509	Sumitomo CRM-1076WA
Bond Wire	0.8mil PdCu	0.8mil PdCu

Cypress also announces the qualification of package-level Test, Finish and Burn-in manufacturing operations at Cypress Manufacturing Limited (CML) in Philippines for Cypress products that were tested at King Yuan Electronics Co., Ltd., (KYEC) Taiwan. There will be no changes to the tester platforms, test program coverage or test methodologies.

Cypress Manufacturing Limited, Philippines is an in-house manufacturing facility and is already a qualified site for Cypress products. This in turn also provides the means for Cypress to continue to meet its customers' IC testing needs as well as delivery commitments in dynamic, changing market conditions.

Below are the Test, Finish and Burn-In locations for FM22L16-55-TG, FM22L16-55-TGTR, CG8395AT and CG8395ATT products.

	Current Location	**Future Location**
Test & Finish	KYEC, Taiwan	CML, Philippines
Burn-in	KYEC, Taiwan	CML, Philippines

Benefit of Change:
Qualification of alternate manufacturing sites is part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

Affected Part Numbers: 8
Affected Parts: See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:
As per the specific list of major changes, this package has been qualified through a series of tests planned in Qualification Test Plans 161614 and 162409. The reports for these QTPs can be found as attachments to this PCN.

Sample Status:
Samples of the 44-Lead TSOP II part numbers are available as indicated in the attached 'Affected Parts List' file. Please contact your Sales Representative as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:
Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of the affected part numbers in the attached file may be sourced from JCET, China or from the other qualified manufacturing sites.

Further, effective from the date of this notification, all shipments of product on the affected parts list will undergo package level Test, Finish and Burn-In operations at CML, Philippines.

Anticipated Impact:
There is no anticipated impact associated with the transfer to product form, fit, function, performance, reliability, quality or product delivery.

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration